IN THE SPECIFICATION:

Please amend paragraph number **[0020]** as follows:

[0020] The apparatus of the invention may be incorporated in a multi-member self-leveling or self-adjusting insert member ~~which~~ that is inserted into a clamp insert carrier. The insert member has a wirebonding window surrounded by a narrow clamping surface wherein compensation for non-uniform leadframe thickness is provided. Preferably, the insert member is formed of a polymer, whereby additional advantages accrue from both the non-conductive electrical property, the low heat conductive property of the insert device, and the degree of elasticity in the polymeric leadframe insert itself. The insert member is configured to provide the required compensation without permanent deformation.

Please amend paragraph number **[0041]** as follows:

[0041] A representative metal leadframe strip 10 used in semiconductor integrated circuit manufacture is shown in drawing FIG. 1. The leadframe strip 10 is a metallized design configured with several, e.g., eight frame sections 12, each frame section having a mounting paddle 14 for mounting a semiconductor device. The leadframe strip 10 includes ~~parallel spaced~~ parallel-spaced strip rails 16, 18 formed with a pattern of indexing openings 26 for handling by automated machinery. The leadframe strip 10 includes within each frame section 12 an array of leadfingers 22 adapted for attachment to the bond pads of a semiconductor device 36 (FIG. 2), hereinafter referred to as a die or dice, during the wirebonding process. In general, the terminal ends 24 of the leadfingers 22 will become the external leads of a completed semiconductor package. In the current technology, the metal thickness 62 (FIG. 2) of single-layer leadframe strips 10 is typically about 20 to 40 μm but may be any thickness which permits accurate wirebonding and sufficient strength of the finished leads for the intended purpose.

Please amend paragraph number **[0045]** as follows:

[0045] A wirebonding platform 32 of a bonding machine is shown with a block heater 34 for heating die 36 and leadfingers (leads) 22 (not shown) of leadframe strip 10 for the

wirebonding operation. The wirebonding platform 32 generally comprises a lower clamp member for holding the leadframe strip 10 while conductive wires 48 are bonded to the leadframe and die 36. The exemplary leadframe clamping apparatus 28 includes (in addition to the wirebonding platform 32) a clamp insert carrier 20, a clamp insert 30 ~~which~~ that rides in the clamp insert carrier 20, a thin resilient member 40, and a clamp insert retainer 50. The clamp insert carrier 20 is generally configured to clamp the opposing strip rails 16, 18 (not shown in FIG. 2) of the leadframe strip 10. An insert window 42 in the clamp insert carrier 20 is configured to hold a clamp insert 30 which has a wirebonding window 44 with a lower peripheral surface 46. The lower peripheral surface 46 comprises an upper clamping surface which engages the upper surface of the leadframe strip 10 about the die 36 for wirebonding, the lower peripheral surface 46 corresponding to peripheral clamping surface 25 in drawing FIGS. 1 and 1A.

Please amend paragraph number **[0071]** as follows:

[0071] There are numerous advantages to the leadframe clamping apparatus 28 as described herein. First, movement of leadfingers during wirebonding is avoided, enabling more uniform and precise bonding. In addition, heat ~~losses~~ loss through the leadframe clamping apparatus ~~are~~ is reduced because of the low heat transfer of the clamp insert. Consistent bonding temperatures are achieved across all leads of the leadframe strip. Thus, the rate of wirebond rejection may be significantly decreased.